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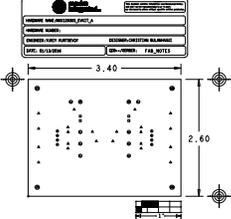
REVISIONS			
REV	DESCRIPTION	APPROVED	DATE

- NOTES:
- UNLESS OTHERWISE SPECIFIED
  1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED). MATERIAL. (USE CHECKED ITEMS FOR MATERIAL)
  2. BOARD MATERIAL:
    - (X) FRA (RHS COMPLIANT) OR EQUIVALENT
    - ( ) ISOLA-FR4000
    - ( ) MELCO-4000-13 OR EQUIVALENT
    - ( ) STORM (RHS COMPLIANT) OR EQUIVALENT
    - ( ) ROGERS 4000/FR4000
    - ( ) ROGERS 400C/FR4000
    - ( ) OTHER \_\_\_\_\_
  3. THE PCB SHALL BE FABRICATED TO IPC-4002, TYPE 1, CLASS 2.
  4. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
  5. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF ULTRA HIGH FLAMMABILITY RATING OF UL-94V0.
  6. OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIED AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.
  7. HOLE & TRIST NOT TO EXCEED 0.0075 IN. (0.175) PER LINEAR INCH. HOLE & TRIST SHOULD BE MEASURED PER IPC-TR-609, METHOD 2.4.2E.

- TOOLING: (USE CHECKED ITEMS FOR TOOLING)
- PHOTO ETCH EXCISION PER ENCLOSED SEMI-FINISH OR OTHER FORMAT FILE. DRILL LOCATION AND SIZE CONTROLLED BY EXCELLENCE DMC DRILL FILE.
  - IF STATED IN THE LAMINATION DIAGRAM, THE DIELECTRIC THICKNESS OF ANY CONTROLLED IMPEDANCE LAYER IS FOR REFERENCE ONLY. FINAL ACCEPTANCE SHALL BE DETERMINED BY THOSE LAYERS HAVING A CHARACTERISTIC IMPEDANCE OF +/-10% OHMS AS STATED IN THE LAMINATION DIAGRAM. THE VENDOR CAN MAKE ADJUSTMENTS AS LONG AS THE STATED IMPEDANCE AND OVERALL BOARD THICKNESS IS MAINTAINED. ANY ADJUSTMENT MADE TO TRACE WIDTH OR SPACING MUST HAVE PRIOR WRITTEN APPROVAL FROM MAXIM.
  - ALL TRACES FILLETED OPTION TO INCREASE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED.
    - ( ) FILLETED
    - (X) NOT FILLETED
  10. LAYER TO LAYER REGISTRATION SHALL BE WITHIN .008 INCHES. LEAD TO LEAD +/- 0.001 INCHES. (USE CHECKED ITEMS FOR PLATING)

- FINISH: (USE CHECKED ITEMS FOR PLATING)
11. PLATING SPECIFICATION:
    - (X) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1.0Z). THE FINISH COPPER WEIGHT IS (1.0Z). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1.0Z) AS A STARTING WEIGHT THE STARTING WEIGHT CAN BE (0.5.0Z) AS LONG AS THE FINISH COPPER WEIGHT IS (1.0Z) UNLESS OTHERWISE SPECIFIED
    - ( ) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1.0Z). THE FINISH COPPER WEIGHT IS (1.0Z). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1.0Z) AS A STARTING WEIGHT THE STARTING WEIGHT CAN BE (0.5.0Z) AS LONG AS THE FINISH COPPER WEIGHT IS (2.0Z) UNLESS OTHERWISE SPECIFIED
    - ( ) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (2.0Z). THE FINISH COPPER WEIGHT IS (2.0Z) MINIMUM. FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (2.0Z) AS A STARTING WEIGHT THE STARTING WEIGHT CAN BE (1.0Z) AS LONG AS THE FINISH COPPER WEIGHT IS (2.0Z) UNLESS OTHERWISE SPECIFIED
    - ( ) OTHER \_\_\_\_\_
  12. CHECK ALL THAT APPLY
    - ( ) ELECTRODEPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN GOLD), GRADE C (MINOR HARDNESS 150-200); CLASS 1 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-G-4520C. GENERAL SURFACING REQUIREMENTS MUST MEET ANECP-4 (NON-CURRENT RES) SECTION 4.5, CLASS 3 (50-100 MICRONS/THICK) OVER ELECTRODEPOSITED NICKEL PLATE IN ACCORDANCE WITH ANECP-4-HOOD, SECTION 4.6, CLASS 3 (100-400 MICRONS/THICK).
    - ( ) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 3-8 MICRO INCHES OVER 100 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
    - ( ) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 2-8 MICRO INCHES OVER 100-MICRON MINIMUM INCHES MINIMUM OF ELECTROLESS NICKEL.
    - ( ) FININGS TO BE GOLD PLATED.
    - (X) LEAD FREE AND RHS COMPLIANT PLATING.
    - ( ) OTHER \_\_\_\_\_
  13. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN .005 DTP. MINIMUM HOLE PLATING OF .001 IN. PLATED HOLES SHALL NOT BE ROUND OR IRREGULAR SO AS TO PREVENT PROPER SOLDER WETTING.
  14. CHECK ALL THAT APPLY
    - (X) GREEN SOLDERMASK OVER BARE COPPER/BARE GOLD (BOTH SIDES) WITH LEADED PHOTO IMAGEABLE INK (LPI) FOR NETWORKS.
    - ( ) GREEN TATVO P38-4000
    - ( ) OTHER \_\_\_\_\_
  15. CHECK ALL THAT APPLY
    - (X) APPLY SOLDERMASK USING A NON-CONDUCTIVE, WHITE EPOXY BASED INK PER ARTWORK.
    - ( ) OTHER \_\_\_\_\_

16. VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYYY MM DD.
17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-836A NETLIST OR OTHER FORMAT FILE. (REQUIRES UNLESS OTHERWISE SPECIFIED IN NOTE) THE PCB SHALL HAVE A VERIFICATION STAMP.
18. A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT.
19. MISCELLANEOUS:
  - (X) IF PRESENT, ALL BLEND/ROTTED VIAS WITH AN ASPECT RATIO >1:1 TO BE PLATED SHOT WITH COPPER WHEN USED AS VIA-IN-PAD OR AS A STAGGED VIA, BLEND/ROTTED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY, UNLESS OTHERWISE SPECIFIED.
  - 20. FOR ALL DRILL INFORMATION REFER TO DRILL CHART.
    - ( ) NON-CONDUCTIVE EPOXY - FILL AND CAP ALL 0.3XXX INCH DRILLED VIAS.
    - ( ) SILVER - FILL AND CAP ALL 0.3XXX INCH DRILLED VIAS.
  - 21. FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY FITS, SCRATCHES, PROBE MARKS OR OTHER DEFECTS THAT COULD AFFECT THE APPEARANCE AND PERFORMANCE OF THE CONTACT SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE. NOT TO EXCEED +/- 0.001" OF FLATNESS.
  - 22. THEFTING:
    - ( ) SUPPLIER MAY ADD THEFTING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
    - (X) SUPPLIER MAY NOT ADD THEFTING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
  - 23. PENMUT
    - ( ) PERMITS TO BE INSTALLED BY SUPPLIER
    - ( ) PERMITS NOT TO BE INSTALLED BY SUPPLIER
    - (X) NOT APPLICABLE



LAYER	MATERIAL	THICKNESS (in.)	DI-ELECTRIC
1 TOP	FOL	TBD	FRA(RHS)/EQIV
2 LP_PAD	FOL	TBD	FRA(RHS)/EQIV
3 LP_PDR	FOL	TBD	FRA(RHS)/EQIV
4 BOTTOM	FOL	TBD	FRA(RHS)/EQIV

THE FINISHED PCB THICKNESS TO BE: 0.0625 +/-0.010

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
△	18.0	+3.0/-16.0	PLATED	22
□	43.311	+3.0/-3.0	PLATED	4
○	45.276	+3.0/-3.0	PLATED	8
⊙	62.992	+3.0/-3.0	PLATED	8
⊙	70.866	+3.0/-3.0	PLATED	2
⊙	125.0	+3.0/-3.0	PLATED	4

TOLERANCES UNLESS OTHERWISE SPECIFIED	THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROPRIETARY TO MAXIM. THE INFORMATION IN THIS DOCUMENT IS NOT TO BE SHOWN, REPRODUCED, OR DISCLOSED TO ANYONE OUTSIDE OF MAXIM WITHOUT PRIOR WRITTEN PERMISSION FROM MAXIM.	
FRACTIONS: $\frac{1}{16}$ $\frac{1}{8}$ $\frac{1}{4}$ $\frac{1}{2}$ $1$ DECIMALS: .XX $\frac{1}{10}$ $\frac{1}{100}$ ANGLES: .XXX $\frac{1}{2}$ $\frac{1}{4}$ $\frac{1}{8}$	HARDWARE NAME: <b>MAXI293XS EVKIT</b>	
MATERIAL:	DRAWN BY: C.BULANHAGUI DATE: 01/2016	HARDWARE NUMBER: MAXI293XS EVKIT
SEE NOTES	CHECKED BY: DATE:	
FINISH:	APPR. BY: DATE:	REV: A
SEE NOTES	APPR. BY: DATE:	NOT TO SCALE   TEMPLATE REV.   SHEET 1 OF 1

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